L Number	Hits	Search Text	DB	Time stamp
_	644		USPAT	2003/07/11 15:32
1_	481		USPAT	2003/08/26 16:57
-	284			2003/03/20 10:37
-	1		USPAT	
-	41		USPAT	2003/08/25 11:43
_	170		USPAT	2003/07/11 11:25
_	65	(216/19).CCLS.	USPAT	2003/07/30 13:17
_	602	(216/20).CCLS.	USPAT	2003/07/11 11:26
_	768		USPAT	2003/07/11 11:27
1_,	337		USPAT	2003/07/11 11:27
- '				
-	788		USPAT	2003/07/11 11:27
-	250		USPAT	2003/08/27 14:08
<u>-</u>	919	(29/846).CCLS.	USPAT	2003/07/11 11:29
-	970	(29/832).CCLS.	USPAT	2003/07/11 11:30
_	90	(29/835).CCLS.	USPAT	2003/07/11 11:31
_	381	printing with (devices or components) with	USPAT;	2003/07/30 12:26
	1	(circuit adj board)	US-PGPUB;	2003/07/30 12:20
		(CIICUIT adj Doald)		
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	78	(method and multilayer and (circuit adj	USPAT;	2003/07/11 13:08
	1	board)).ti.	US-PGPUB	1
	159		JPO	2003/07/11 13:09
	1 139		1050	2003/07/11 13:09
	_	board)).ti.		000046-45-
-	8	((vias or holes) and (circuit adj	JPO	2003/07/11 13:10
	_	board)).ti.		
-	66	((vias or holes) and (circuit adj	USPAT;	2003/07/11 13:10
		board)).ti.	US-PGPUB	
_	74		USPAT;	2003/07/11 15:33
	,4		1	2003/07/11 15:33
		ink	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM TDB	
_	55	((solder adj mask) with printing).ab.	USPAT;	2003/07/14 10:17
		(too and and made, when princing, tab.	US-PGPUB;	2003/01/11 10:17
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	152	((solder adj mask) with printing) and	USPAT;	2003/08/27 15:23
		(circuit adj board)	US-PGPUB;	
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
			DERWENT;	
		·		
	000		IBM_TDB	
-	223	(circuit adj board).ti. and (plating near5	USPAT;	2003/08/26 15:26
1		thickness)	US-PGPUB	
-	111	(circuit adj board).ti. and mask and	USPAT;	2003/07/14 10:39
		(plating near5 thickness)	US-PGPUB	
] _	49	(circuit adj board).ti. and mask and	USPAT;	2003/07/14 10:40
1		printing.clm.	•	2005/07/14 10:40
1_	241		US-PGPUB	1 2002 /07 /14 10 11
	241	(circuit adj board).ti. and ((plating or	USPAT;	2003/07/14 10:41
		solder) adj mask)	US-PGPUB	l
-	15	(circuit adj board).ti. and	USPAT;	2003/07/14 10:41
		(press-bonding)	US-PGPUB	
-	563	(circuit adj board).ti. and (laminating)	USPAT;	2003/07/14 10:42
j l		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB	,,
_	228	print\$3 and ((direct or off-set) adj		2002/07/14 10 41
	220	mode)	USPAT;	2003/07/14 10:44
	216		US-PGPUB	
-	216	((electrophotographic or	USPAT;	2003/07/14 10:49
		electro-photographic) adj print\$3) and	US-PGPUB	
		(circuit adj board)	,	
-	7	((((ink adj jet)or ink-jet) adj print\$3)	USPAT;	2003/07/14 10:49
		and (circuit adj board)).ab.	US-PGPUB	-555,57,11 10.49
<u>_</u>	222	((lithographic) adj print\$3) and (circuit		2003/07/14 10:50
	222		USPAT;	2003/07/14 10:50
	2	adj board)	US-PGPUB	
-	341	(printed adj (resistor or cappacitor or	USPAT;	2003/07/14 10:51
		inductor))	US-PGPUB	
-	492	(printed adj (resistor\$1 or cappacitor\$1	USPAT;	2003/07/14 10:52
		or inductor\$1))	US-PGPUB	
-	0	(printed with (resistor\$1 and cappacitor\$1		2003/07/14 10:50
	. 0		USPAT;	2003/07/14 10:52
	430	and inductor\$1))	US-PGPUB	
; -	439	printed adj resistor\$1	USPAT;	2003/07/14 11:40
			US-PGPUB	

		I maintand add industrant	USPAT;	2003/07/14 10:54
-	62	printed adj inductor\$1	US-PGPUB	2003/07/14 10:54
-	112	printed adj capacitor\$1	USPAT; US-PGPUB	2003/07/14 10:53
_	245	((printed adj resistor\$1) or (printed adj capacitor\$1) or (printed adj inductor\$1))	USPAT; US-PGPUB	2003/07/14 10:56
-	424	and (circuit adj board) printed adj resistor\$1	EPO; JPO; DERWENT;	2003/07/14 11:41
_	1436	(copper adj (clad or cladding)) and ((circuit or wiring) adj board)	IBM_TDB EPO; JPO; DERWENT; IBM TDB	2003/07/14 11:43
-	3145	(copper adj (clad or cladding)) and ((circuit or wiring) adj board)	USPAT; US-PGPUB	2003/07/14 11:44
-	1151	((copper adj (clad or cladding)) and ((circuit or wiring) adj board)) and	USPAT; US-PGPUB	2003/07/14 11:44
-	2388	<pre>(mask\$3 and etch\$3) (copper adj (clad or cladding)) and ((circuit or wiring) adj board) and etch\$3</pre>	USPAT; US-PGPUB	2003/07/14 11:45
-	10	(copper adj (clad or cladding)) and ((circuit or wiring) adj board) and (printed adj (resistor\$1 or capacitor\$1 or	USPAT; US-PGPUB	2003/07/14 11:48
-	1077	<pre>inductor\$1)) (copper adj (clad or cladding)) and ((circuit or wiring) adj board) and ((holes or vias) with (plated or plating))</pre>	USPAT; US-PGPUB	2003/07/14 11:50
_	32	((copper adj (clad or cladding)) and ((circuit or wiring) adj board)) and (seed adj layer)	USPAT; US-PGPUB	2003/07/14 11:51
-	384	((printing or screening) with (mask)) and (circuit adj board).ti.	USPAT; US-PGPUB; EPO; JPO;	2003/07/30 12:28
			DERWENT; IBM_TDB	
-	240 760	(216/39).CCLS. (216/41).CCLS.	USPAT USPAT	2003/07/30 13:19 2003/07/30 13:18
-	353	(216/33).CCLS.	USPAT	2003/07/30 13:16
-	100		USPAT	2003/07/30 13:55
	96092	((circuit or wiring) adj board).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/25 11:53
-	260	(((circuit or wiring) adj board).ti.) and print\$3 near2 traces	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/25 12:20
_	2	("5826329").PN.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/25 12:16
-	9	("2582685" "3350250" "3778899" "4343083" "4403410" "4991287" "5013397" "5184111" "5426850").PN.	IBM_TDB USPAT	2003/08/25 11:58
] -	1	5826329.URPN.	USPAT	2003/08/25 12:16
-	2	("5932280").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/08/25 12:16
-	5	("3909680" "4722765" "4991287" "5379190" "5826329").PN.	USPAT	2003/08/25 12:17
-		5932280.URPN.	USPAT	2003/08/25 12:18
	0 9	5932280.URPN. (((circuit or wiring) adj board).ti.) and direct adj printing	USPAT; USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/08/25 12:18 2003/08/25 12:22
			IBM_TDB	

- 58 (((circuit or wiring) adj board).ti.) and USPAT; 200 offset adj printing US-PGPUB;	03/08/25 12:48
EPO; JPO;	
DERWENT;	
IBM_TDB	03/00/25 10-02
- 17 (((circuit or wiring) adj board).ti.) and USPAT; 200 lithographic adj printing US-PGPUB;	03/08/25 12:23
EPO; JPO;	
DERWENT;	
- 3 (((circuit or wiring) add board).ti.) and USPAT; 200	02/00/25 12:04
- 3 (((circuit or wiring) adj board).ti.) and USPAT; 200 off-set adj printing US-PGPUB;	03/08/25 12:24
EPO; JPO;	
DERWENT;	
IBM_TDB I657 (((circuit or wiring) adj board).ti.) and USPAT; 200	03/08/25 12:25
screen adj printing US-PGPUB;	03/08/23 12:23
EPO; JPO;	
DERWENT;	
- 103 (((circuit or wiring) adj board).ti.) and USPAT; 200	03/08/25 12:25
(screen adj printing) same (resistor\$1 or US-PGPUB;	03/06/23 12:23
capacitor\$1) EPO; JPO;	
DERWENT;	
- 24 (((circuit or wiring) adj board).ti.) and USPAT; 200	03/08/25 12:33
(screen adj printing) same (resistor\$1 and US-PGPUB;	03/06/23 12:33
capacitor\$1) EPO; JPO;	
DERWENT;	
IBM_TDB	03/08/25 12:30
((ink-jet or inkjet) adj printing) US-PGPUB;	03/06/23 12:30
EPO; JPO;	
DERWENT;	
IBM_TDB 1303 (((circuit or wiring) adj board).ti.) and USPAT; 200	03/08/25 12:49
(solder adj resist) with print\$3 US-PGPUB;	03/06/23 12:49
EPO; JPO;	
DERWENT;	
IBM_TDB I65 (((circuit or wiring) adj board).ti.) and USPAT; 200	03/08/25 12:55
(solder adj resist) with print\$3 with US-PGPUB;	00,00,20 12.00
(inkjet or lithographic or screen or EPO; JPO;	
relief or press) DERWENT; IBM TDB	
	03/08/25 12:58
(solder adj resist) with print\$3 with US-PGPUB;	
(inkjet or lithographic or relief or EPO; JPO;	
press) DERWENT; IBM TDB	•
	03/08/25 16:30
(printing with (press and lithographic)) US-PGPUB;	· ·
EPO; JPO;	
DERWENT; IBM TDB	
l	03/08/26 14:39
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 4 ((printing) and (fusable adj ink)) and USPĀT; 200	03/08/26 14:39
(silver or Ag or palladium or Pd) US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	
- 330 (printing) with (fusible adj ink) USPAT; 200	03/08/26 14:39
US-PGPUB;	
EPO; JPO; DERWENT;	
IBM TDB	

-	83	((printing) and (fusible adj ink)) and	USPAT;	2003/08/26 14:44
		(silver or Ag or palladium or Pd)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	,
			IBM TDB	
-	3	((printing) and (fusible adj ink)) and	USPAT;	2003/08/26 14:42
		(silver or Ag or palladium or Pd) and	US-PGPUB;	
		(circuit adj board)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	13	((printing) and (fusible adj ink)) and	USPAT;	2003/08/26 15:27
		(palladium or Pd)	US-PGPUB;	,,
		(1)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
l _	377	(circuit adj board).ti. and (plat\$3 same	USPAT;	2003/08/26 15:51
]	thickness) and mask\$3	US-PGPUB	2003/00/20 13:31
_	0	"09890471"		2002/09/26 15:52
-		09090471	USPAT; US-PGPUB	2003/08/26 15:52
	602	(21 C / 20) COT C		2002/00/26 17:00
-	603		USPAT	2003/08/26 17:09
-	58	((216/20).CCLS.) and (circuit adj	USPAT;	2003/08/26 16:58
		board).ti.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM_TDB	
-	7		USPAT;	2003/08/27 14:19
		and (circuit adj board)).ti. and ((double	US-PGPUB;	
		adj sided) or double-sided).ab.	EPO; JPO;	
			DERWENT;	i
İ			IBM_TDB	
-	39	(method and (multi-layer or multilayer)	USPAT;	2003/08/26 17:11
		and (circuit adj board)).ti. and ((double	US-PGPUB;	
		adj sided) or double-sided)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	. 37	3660726.URPN.	USPAT	2003/08/26 17:13
-	649	(29/852).CCLS.	USPAT	2003/08/27 14:09
-	611	(method and (multi-layer or multilayer)	USPAT;	2003/08/27 14:21
		and (circuit adj board)).ti.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1380	((multi-layer or multilayer) and (circuit	USPAT;	2003/08/27 14:23
		adj board)).ti.	US-PGPUB;	1 100,00,2, 14.25
ĺ			JPO	
<u>_</u>	333	((multi-layer or multilayer) and (circuit	USPAT;	2003/08/27 14:23
		adj board)).ti.	US-PGPUB	2003/00/2/ 14:23
_	27	((solder adj mask) with printing) and	USPAT;	2003/08/27 15:26
		(circuit adj board).ti.	US-PGPUB	2003/00/2/ 13:26
_	2	("4991287").PN.		2002/09/27 16:00
-		(4331201).FN.	USPAT;	2003/08/27 16:22
			US-PGPUB;	
			EPO; JPO;	
}			DERWENT;	
i	_ [/#0500.605# / #4400.440#: -	IBM_TDB	
	2	("2582685" "4403410").PN.	USPAT	2003/08/27 16:22